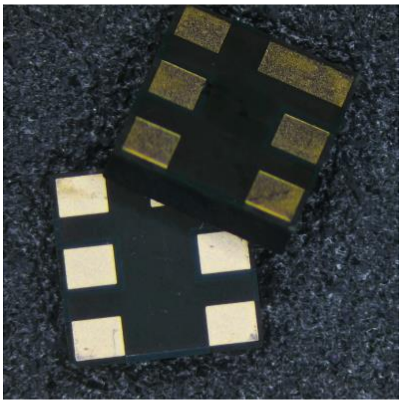
Features

- For 1618MHz Band application
- FBAR (Film Bulk Acoustic Resonator) technology
- Low Insertion Loss
  - ✓ 0.7dB (typical @1618MHz)
- Plastic Chip Scale Package (CSP)
  - ✓ Standard size : 3.0mm*3.0mm*0.7mm
- Moisture Sensitivity: MSL3

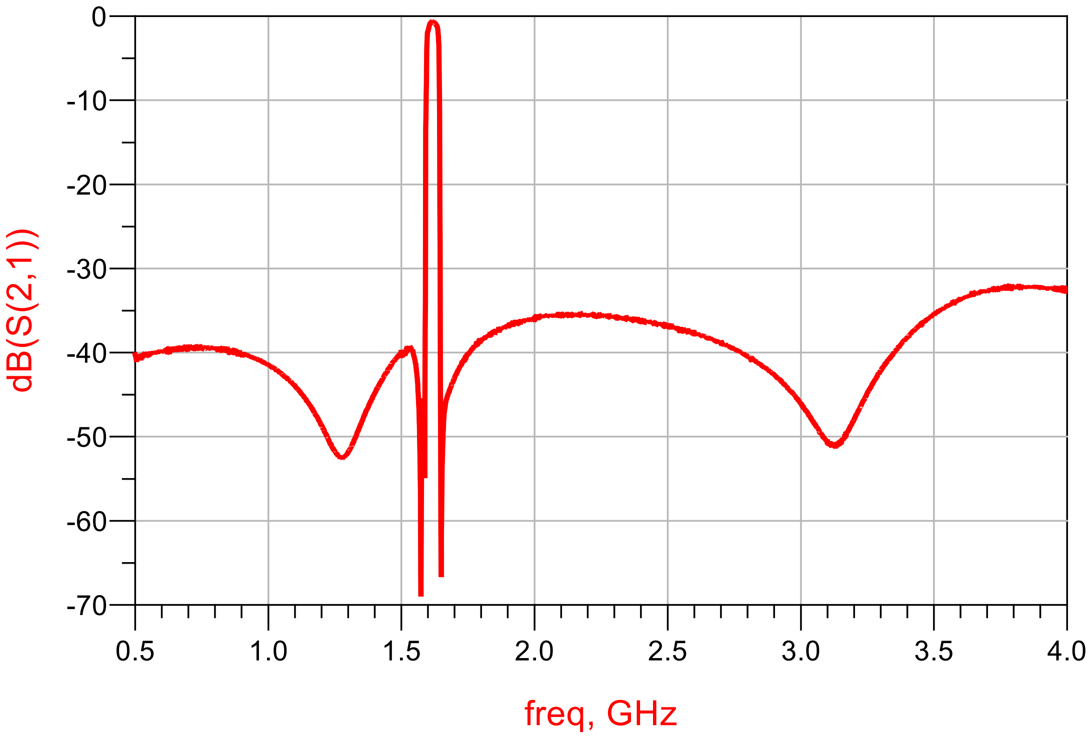


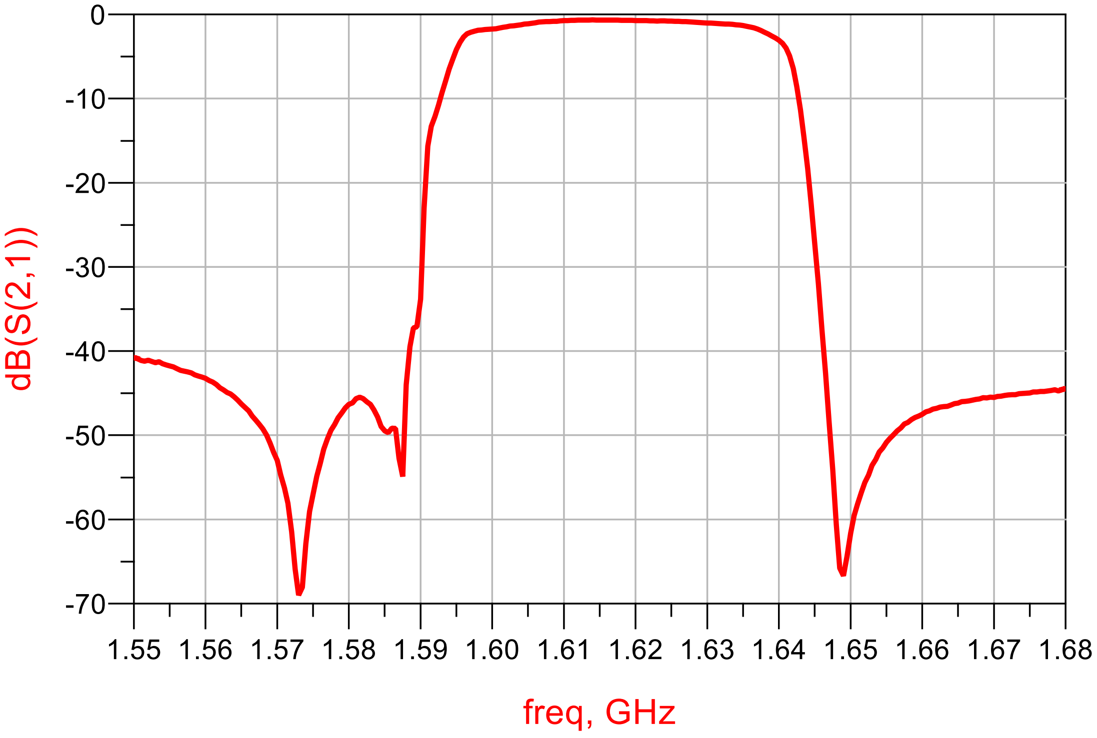
Electrical Specifications*, Z_0=50Ω, T_{SPEC}=-55℃~+85℃

Parameter		Min. For T_{SPEC}	Typ. @+25℃	Max. For T_{SPEC}	Unit
Frequency		1618			MHz
Insertion Loss(1607 ~ 1629MHz)		\	0.8	1.6	dB
I.L. Ripple(1607 ~ 1629MHz)		\	0.4	1.0	dB
1dB BW		22	\	\	dB
VSWR(1607 ~ 1629MHz)		\	1.3	1.8	
Attenuation	1258~1278MHz	40	51	\	dB
	1559~1578MHz	37	42	\	dB
Power Handling Capability		32	\	\	dBm
Group delay ripple(1607 ~ 1629MHz)		\	7	20	ns

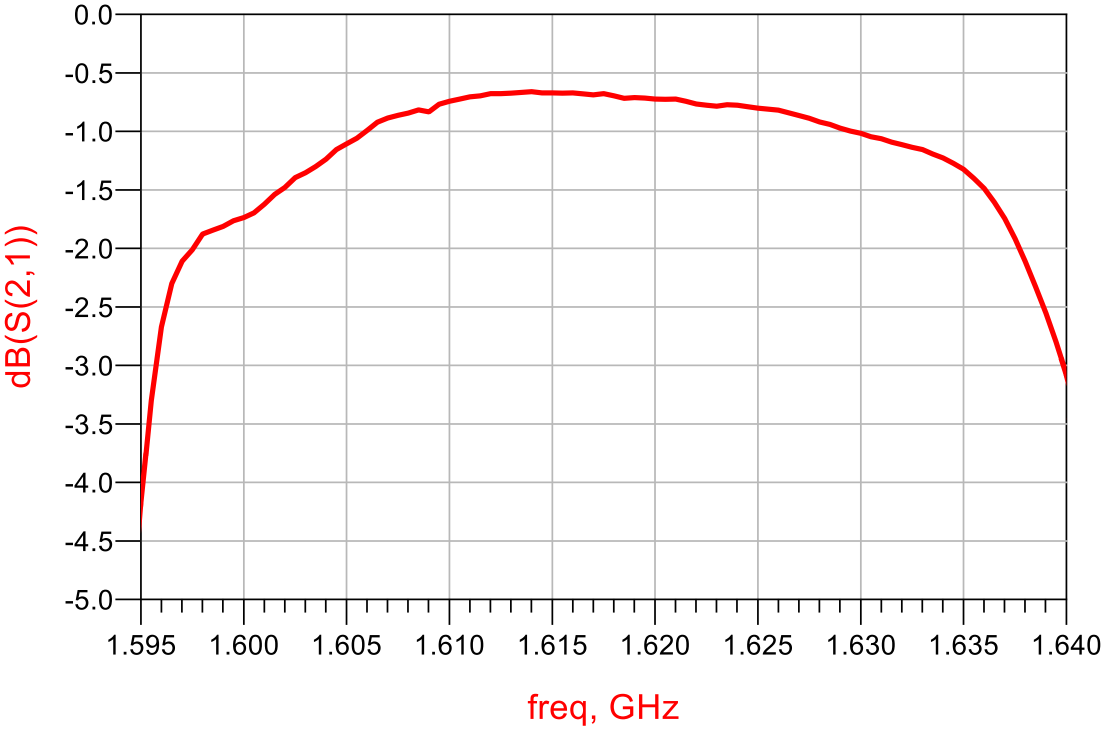
*: EVB Feedline loss is de-embedding.

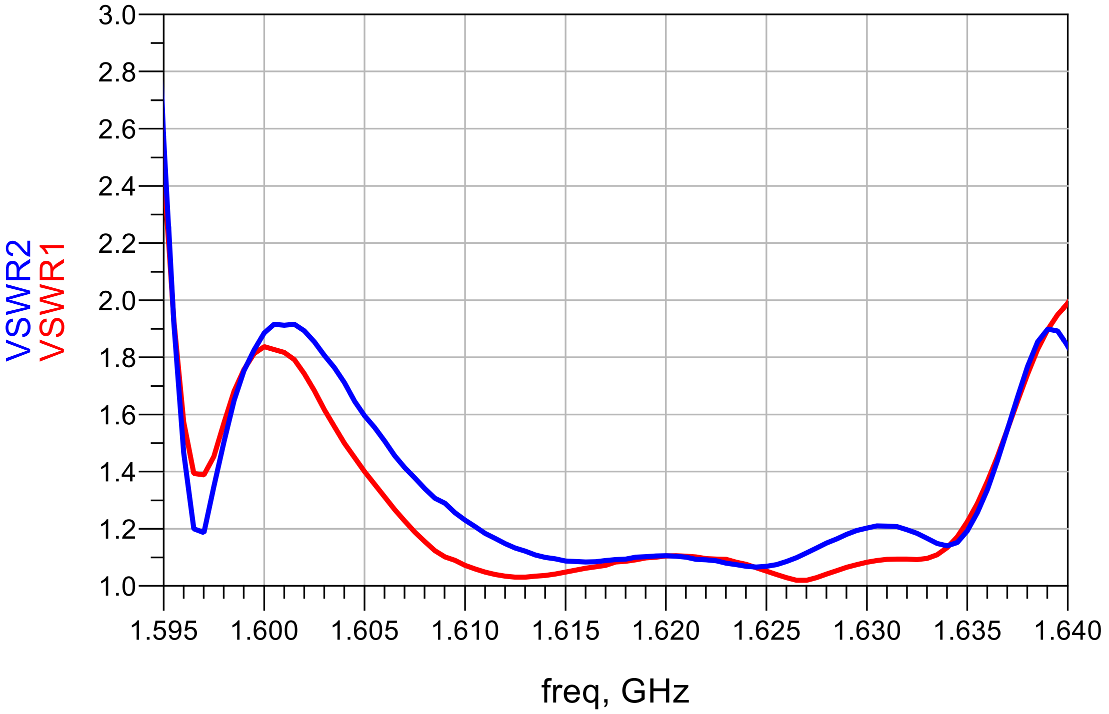
Typical Performance at Tc = 25°C



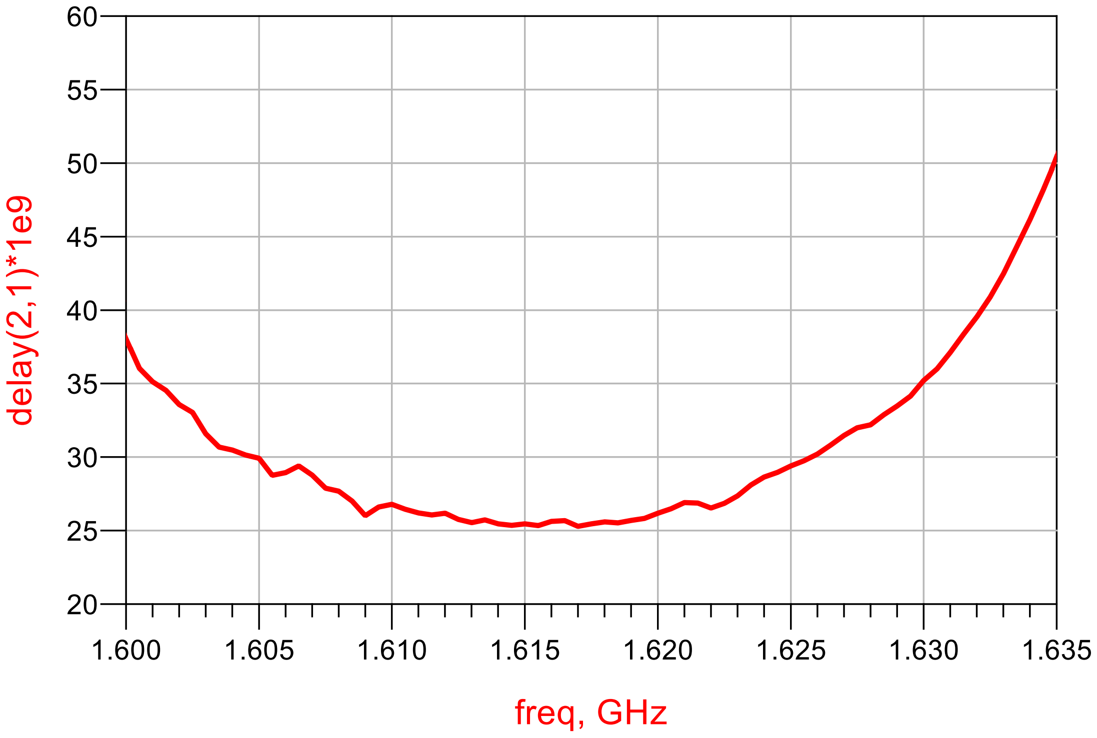


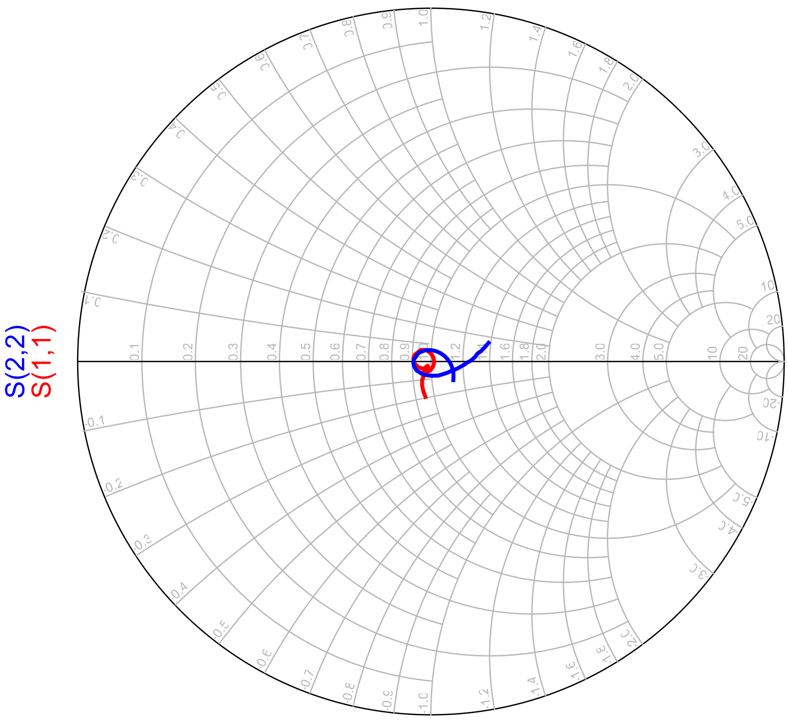
Typical Performance at Tc = 25°C





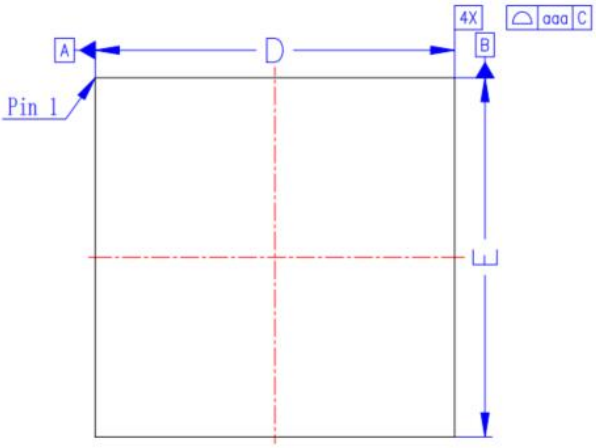
Typical Performance at Tc = 25°C



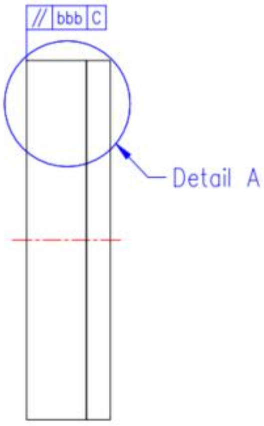


freq (1.607 GHz to 1.629 GHz)

Package Outline Drawing(Unit:mm)



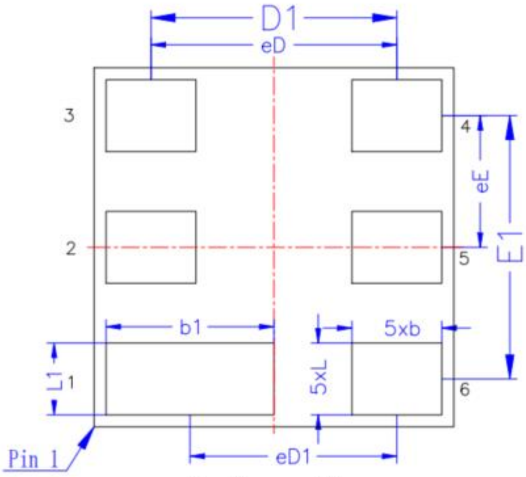
Top View



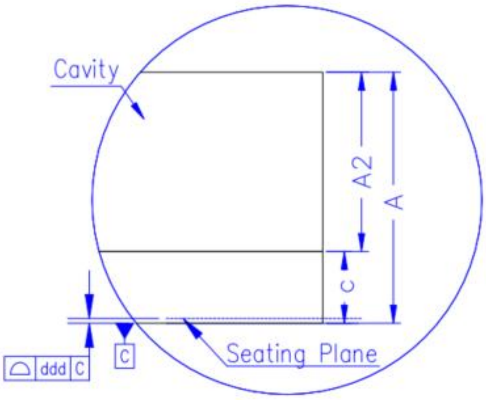
Side View

(Units Of Measure=Millimeter)

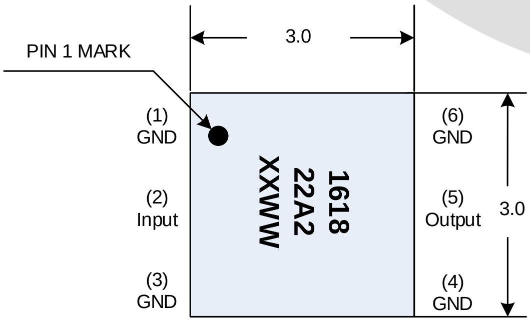
Item		Symbol	Common Dimensions		
			MIN.	NOM.	MAX.
Body Size	X	D	2.900	3.000	3.100
	Y	E	2.900	3.000	3.100
Land Pitch	X	eD	2.050		
	X	eD1	1.725		
	Y	eE	1.100		
Total Thickness		A	0.650	0.700	0.750
Mold Cap		A2	0.500REF		
Substrate Thickness		c	0.170	0.200	0.230
Land Size		b	0.700	0.750	0.800
		L	0.550	0.600	0.650
		b1	1.350	1.400	1.450
		L1	0.550	0.600	0.650
Package Edge Tolerance		aaa	0.100		
Package Flatness		bbb	0.100		
Coplanarity		ddd	0.100		
Land Count		n	6		
Edge Land center to center	X	D1	2.050		
	Y	E1	2.200		



Bottom View



Detail A(3:1)
Roted 90°



TOP VIEW

Notes:
1618、22A2为固定字符，XXWW为批次编码。

Revision History

Revision	Date	Description
A	2025-11-03	Initial document